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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/736,864	12/14/2000	Takahiro Iijima	CU-2417 RJS	8303

7590

05/22/2003

Ladas & Parry
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EXAMINER

CHU, CHRIS C

ART UNIT

PAPER NUMBER

2815

DATE MAILED: 05/22/2003

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary

Application No.

09/736,864

Applicant(s)

IIJIMA ET AL.

Examiner

Chris C. Chu

Art Unit

2815

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133).
- Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 07 February 2003.
- 2a) ☐ This action is **FINAL**. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 1 - 14 is/are pending in the application.
- 4a) Of the above claim(s) 2 - 10, 12 and 14 is/are withdrawn from consideration.
- 5) ☐ Claim(s) _____ is/are allowed.
- 6) ☒ Claim(s) 1, 11 and 13 is/are rejected.
- 7) ☐ Claim(s) _____ is/are objected to.
- 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on _____ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
- Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
- 11) ☐ The proposed drawing correction filed on _____ is: a) ☐ approved b) ☐ disapproved by the Examiner.
- If approved, corrected drawings are required in reply to this Office action.
- 12) ☐ The oath or declaration is objected to by the Examiner.

Priority under 35 U.S.C. §§ 119 and 120

- 13) ☒ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☒ All b) ☐ Some * c) ☐ None of:
1. ☒ Certified copies of the priority documents have been received.
2. ☐ Certified copies of the priority documents have been received in Application No. _____.
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).
- * See the attached detailed Office action for a list of the certified copies not received.
- 14) ☐ Acknowledgment is made of a claim for domestic priority under 35 U.S.C. § 119(e) (to a provisional application).
- a) ☐ The translation of the foreign language provisional application has been received.
- 15) ☐ Acknowledgment is made of a claim for domestic priority under 35 U.S.C. §§ 120 and/or 121.

Attachment(s)

- 1) ☒ Notice of References Cited (PTO-892)
- 2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) ☐ Information Disclosure Statement(s) (PTO-1449) Paper No(s) _____
- 4) ☐ Interview Summary (PTO-413) Paper No(s). _____
- 5) ☐ Notice of Informal Patent Application (PTO-152)
- 6) ☐ Other: _____

DETAILED ACTION

Request for Continued Examination

1. A request for continued examination (RCE) under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on March 3, 2003 has been entered. An action on the RCE follows.
2. Applicant's amendment filed on February 7, 2003 has been received and entered in the case.

Drawings

3. The proposed drawing correction and/or the proposed substitute sheets of drawings, filed on September 4, 2002 have been disapproved because it is not in the form of a pen-and-ink sketch showing changes in red ink or with the changes otherwise highlighted. See MPEP § 608.02(v). A proper drawing correction or corrected drawings are required in reply to the

Art Unit: 2815

Office action to avoid abandonment of the application. The correction to the drawings will not be held in abeyance.

Since applicant has not responded or amended to the objection to the proposed drawing correction in the above paragraph, the objection is maintained.

Claim Objections

4. Claim 1 is objected to because of the following informalities: in line 8, “an insulting” should be --an insulating or insulation--. Appropriate correction is required.

Claim Rejections - 35 USC § 103

5. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

6. Claims 1, 11 and 13 are rejected under 35 U.S.C. 103(a) as being unpatentable over Lan et al. in view of Yamaguchi et al., and further in view of Usagawa et al.

Regarding claim 1, Lan et al. discloses in Fig. 5B and Fig. 7A a multilayer interconnection substrate comprising:

Art Unit: 2815

- an uppermost interconnection layer (443) having a plurality of terminal pads (521A and 521C) formed at positions corresponding to a plurality of external connection terminals (721) provided on a semiconductor element (720) which is to be mounted on said multilayer interconnection substrate;
- a metal column (541A) formed on each of said terminal pads, and having a top surface;
- an insulating layer (441) formed on said uppermost interconnection layer so that a gap (551A) is formed between the insulating layer and an outer peripheral surface of said resin film.

Lan et al. does not disclose a resin film covering a side surface of said metal column, and having a top surface. However, Yamaguchi et al. discloses in Fig. 5 and column 10, lines 15 ~ 16 a resin film (30) covering a side surface of a metal column (28), and having a top surface; the top surface of the metal column and the top surface of the resin film covering the side surface of the metal column are formed at the same level of height; and the top surface of the metal column is surrounded by and exposed on the resin film so that the top surface of the resin film forms a pad for connection with a semi-conductor element. Thus, it would have been obvious to one of ordinary skill in the art at the time when the invention was made to modify Lan et al. by using the resin film as taught by Yamaguchi et al. The ordinary artisan would have been motivated to modify Lan et al. in the manner described above for at least the purpose of preventing the bumps from being oxidized (column 3, lines 32 ~ 37).

Further, Lan et al. does not disclose an upper end surface of each metal column being at the same height as an upper surface of the insulating layer. Usagawa et al. discloses in Fig. 13c

Art Unit: 2815

an upper end surface of each metal column (30) being at the same height as an upper surface of an insulating layer (72). Thus, it would have been obvious to one of ordinary skill in the art at the time when the invention was made to modify Lan et al. by using the resin film as taught by Usagawa et al. The ordinary artisan would have been motivated to modify Lan et al. in the manner described above for at least the purpose of decreasing manufacturing cost.

Regarding claim 11, Lan et al. discloses in Fig. 5B and Fig. 7A a semiconductor device comprising:

- a multilayer interconnection substrate which comprises
- an uppermost interconnection layer (443) having
 - o a plurality of terminal pads (521A and 521C) formed at positions corresponding to a plurality of external connection terminals (721) provided on a semiconductor element (720) which is to be mounted on said multilayer interconnection substrate;
 - o a metal column (541A) formed on each of said terminal pads, and having a top surface;
 - o an insulating layer (441) formed on said uppermost interconnection layer so that a gap (551A) is formed between the insulating layer and an outer peripheral surface of said resin film.

Lan et al. does not disclose a resin film covering a side surface of said metal column, and having a top surface. However, Yamaguchi et al. discloses in Fig. 5 and column 10, lines 15 ~ 16 a resin film (30) covering a side surface of a metal column (28), and having a top surface; the top

Art Unit: 2815

surface of the metal column and the top surface of the resin film covering the side surface of the metal column are formed at the same level of height; and the top surface of the metal column is surrounded by and exposed on the resin film so that the top surface of the resin film forms a pad for connection with a semi-conductor element. Thus, it would have been obvious to one of ordinary skill in the art at the time when the invention was made to modify Lan et al. by using the resin film as taught by Yamaguchi et al. The ordinary artisan would have been motivated to modify Lan et al. in the manner described above for at least the purpose of preventing the bumps from being oxidized (column 3, lines 32 ~ 37).

Further, Lan et al. does not disclose an upper end surface of each metal column being at the same height as an upper surface of the insulating layer. Usagawa et al. discloses in Fig. 13c an upper end surface of each metal column (30) being at the same height as an upper surface of an insulating layer (72). Thus, it would have been obvious to one of ordinary skill in the art at the time when the invention was made to modify Lan et al. by using the resin film as taught by Usagawa et al. The ordinary artisan would have been motivated to modify Lan et al. in the manner described above for at least the purpose of decreasing manufacturing cost.

Regarding claim 13, Lan et al. discloses in Fig. 5B and Fig. 7A a semiconductor device comprising:

- multilayer interconnection substrate manufactured by
 - o forming a plurality of terminal pads (521A and 521C) in an uppermost interconnection layer (443);
 - o forming an insulating layer (441) on said uppermost interconnection layer;

Art Unit: 2815

- forming openings (the area of 551A and 541A) in said insulating layer, the openings located at positions corresponding to said terminal pads;
- filling each of said openings with metal particles;
- forming a metal column (541A) in each of said openings by heating said metal particles at a temperature which melts said metal particles so as to define a metal column top surface; and
- removing a part of said insulating layer near but not adjacent to a peripheral side of said metal column, so that a gap (551A) is formed around but not adjacent to said peripheral side of said metal column.

Lan et al. does not disclose a part of said insulating layer adjacent to said peripheral side of said metal column. However, Yamaguchi et al. discloses in Fig. 5 and column 10, lines 15 ~ 16 a part of an insulating layer (30) adjacent to a peripheral side of a metal column (28). Thus, it would have been obvious to one of ordinary skill in the art at the time when the invention was made to modify Lan et al. by using the insulating layer as taught by Yamaguchi et al. The ordinary artisan would have been motivated to modify Lan et al. in the manner described above for at least the purpose of preventing the bumps from being oxidized (column 3, lines 32 ~ 37).

Further, Lan et al. does not disclose an upper end surface of each metal column being at the same height as an upper surface of the insulating layer. Usagawa et al. discloses in Fig. 13c an upper end surface of each metal column (30) being at the same height as an upper surface of an insulating layer (72). Thus, it would have been obvious to one of ordinary skill in the art at the time when the invention was made to modify Lan et al. by using the resin film as taught by

Usagawa et al. The ordinary artisan would have been motivated to modify Lan et al. in the manner described above for at least the purpose of decreasing manufacturing cost.

Furthermore, the claim 13 is product-by-process claim, even though product-by-process claim is limited by and defined by the process, determination of patentability is based upon the product itself. The patentability of a product does not depend on its method of production. If the product in product-by-process claim is the same as or obvious from a product of the prior art, the claim is unpatentable even though the prior product is made by a different process. In re Thorpe, 227 USPQ 964, 966 (Fed. Cir. 1985) (citations omitted). A “product by process” claim is directed to the product per se, no matter how actually made, In re Hirao, **190 USPQ 15 at 17** (footnote 3). See also In re Brown, **173 USPQ 685**; In re Luck, **177 USPQ 523**; In re Fessmann, **180 USPQ 324**; In re Avery, **186 USPQ 116**; In re Wertheim, **191 USPQ 90 (209 USPQ 254** does not deal with this issue); and In re Marosi et al., **218 USPQ 289** final product per se which must be determined in a “product by, all of” claim, and not the patentability of the process, and that an old or obvious product, whether claimed in “product by process” claims or not. Note that Applicant has the burden of proof in such cases, as the above caselaw makes clear.

Response to Arguments

7. Applicant's arguments with respect to claims 1, 11 and 13 have been considered but are moot in view of the new ground(s) of rejection.

Conclusion

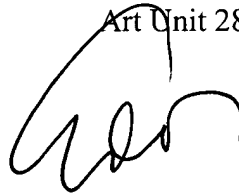
8. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. Yokoyama, Shinomiya and Tsuchitani et al. disclose a semiconductor device.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Chris C. Chu whose telephone number is (703) 305-6194. The examiner can normally be reached on M-F (10:30 - 7:00).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Eddie C. Lee can be reached on (703) 308-1690. The fax phone numbers for the organization where this application or proceeding is assigned are (703) 308-7382 for regular communications and (703) 308-7722 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.

Chris C. Chu
Examiner
Art Unit 2815



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SUPERVISORY PATENT EXAMINER
TECHNOLOGY CENTER 2800

c.c.
May 18, 2003